

12 June 2003

09/831, 763

L Number	Hits	Search Text	DB	Time stamp
-	1187	205/\$.ccls. and (puls\$3 with current)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:51
-	566	(205/\$.ccls. and (puls\$3 with current)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:50
-	1232	205/\$.ccls. and (puls\$3 with (current or revers\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:51
-	8136	205/\$.ccls. and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:52
-	2472	205/\$.ccls. and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:52
-	189	(205/\$.ccls. and (puls\$3 with (current or revers\$3))) and (205/\$.ccls. and copper) and (205/\$.ccls. and semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:52
-	150	((205/\$.ccls. and (puls\$3 with (current or revers\$3))) and (205/\$.ccls. and copper) and (205/\$.ccls. and semiconductor)) and (recess or trench or via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 15:01
-	22	((205/\$.ccls. and (puls\$3 with (current or revers\$3))) and (205/\$.ccls. and copper) and (205/\$.ccls. and semiconductor)) and (recess or trench or via or hole)) and ((inert or noble or titanium) near (anode or electrode or counterelectrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:20
-	2	"6432293"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 15:24
-	1	2000-642506.NRAN.	DERWENT	2003/06/11 15:22
-	61	205/\$.ccls. and damascen and puls\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 16:06

-	258	205/\$.ccls. and ((cathodic or plating or forward) adj (current or pulse)) and ((anodic or polishing or etching or dissolution) adj (current or pulse))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 16:09
-	43	(205/\$.ccls. and ((cathodic or plating or forward) adj (current or pulse)) and ((anodic or polishing or etching or dissolution) adj (current or pulse))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 16:09
-	2	gb-2214520-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 08:47
-	35091	205/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:03
-	2587	205/\$.ccls. and (semiconductor or (silicon adj wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:19
-	1589	(205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (recess or trench or via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:20
-	918	((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (recess or trench or via or hole)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:20
-	286	((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (recess or trench or via or hole)) and (copper near (electroplat\$4 or electrochem\$6 or electroly\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:31
-	48	((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (recess or trench or via or hole)) and (copper near (electroplat\$4 or electrochem\$6 or electroly\$6)) and (iron or "fe(II)" or "fe(III)" or feI or ((ferric or ferrous) adj ion))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:31
-	336	(205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (copper near (electroplat\$4 or electrochem\$6 or electroly\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:31

-	63	((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (copper n ar (electroplat\$4 or el ctrochem\$6 or electroly\$6))) and (iron or "fe(II)" or "fe(III)" or fe! or ((ferric or f rrous) adj ion))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:31
-	15	(((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (copper near (electroplat\$4 or electrochem\$6 or electroly\$6))) and (iron or "fe(II)" or "fe(III)" or fe! or ((ferric or ferrous) adj ion))) not (((205/\$.ccls. and (semiconductor or (silicon adj wafer))) and (recess or trench or via or hole)) and (copper near (electroplat\$4 or electrochem\$6 or electroly\$6))) and (iron or "fe(II)" or "fe(III)" or fe! or ((ferric or ferrous) adj ion)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:34
-	782	205/291-298.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:34
-	118	205/291-298.ccls. and (iron or fe! or ferrous or ferric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:34
-	106	205/291-298.ccls. and (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:35
-	28	(205/291-298.ccls. and (iron or fe! or ferrous or ferric)) and (205/291-298.ccls. and (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:37
-	2	6099711.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:38
-	9	"6099711"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 09:38
-	1	1997-282330.NRAN.	DERWENT	2003/06/12 09:38
-	3205	205/101,102,103,104,118,122,123,157,183,220,221,291,292,293,294,295,296,297,298,299,300,301,302,303,304,305,306,307,308,309,310,311,312,313,314,315,316,317,318,319,320,321,322,323,324,325,326,327,328,329,330,331,332,333,334,335,336,337,338,339,340,341,342,343,344,345,346,347,348,349,350,351,352,353,354,355,356,357,358,359,360,361,362,363,364,365,366,367,368,369,370,371,372,373,374,375,376,377,378,379,380,381,382,383,384,385,386,387,388,389,390,391,392,393,394,395,396,397,398,399,400,401,402,403,404,405,406,407,408,409,410,411,412,413,414,415,416,417,418,419,420,421,422,423,424,425,426,427,428,429,430,431,432,433,434,435,436,437,438,439,440,441,442,443,444,445,446,447,448,449,450,451,452,453,454,455,456,457,458,459,460,461,462,463,464,465,466,467,468,469,470,471,472,473,474,475,476,477,478,479,480,481,482,483,484,485,486,487,488,489,490,491,492,493,494,495,496,497,498,499,500,501,502,503,504,505,506,507,508,509,510,511,512,513,514,515,516,517,518,519,520,521,522,523,524,525,526,527,528,529,530,531,532,533,534,535,536,537,538,539,540,541,542,543,544,545,546,547,548,549,550,551,552,553,554,555,556,557,558,559,560,561,562,563,564,565,566,567,568,569,570,571,572,573,574,575,576,577,578,579,580,581,582,583,584,585,586,587,588,589,590,591,592,593,594,595,596,597,598,599,600,601,602,603,604,605,606,607,608,609,610,611,612,613,614,615,616,617,618,619,620,621,622,623,624,625,626,627,628,629,630,631,632,633,634,635,636,637,638,639,640,641,642,643,644,645,646,647,648,649,650,651,652,653,654,655,656,657,658,659,660,661,662,663,664,665,666,667,668,669,670,671,672,673,674,675,676,677,678,679,680,681,682,683,684,685,686,687,688,689,690,691,692,693,694,695,696,697,698,699,700,701,702,703,704,705,706,707,708,709,710,711,712,713,714,715,716,717,718,719,720,721,722,723,724,725,726,727,728,729,730,731,732,733,734,735,736,737,738,739,740,741,742,743,744,745,746,747,748,749,750,751,752,753,754,755,756,757,758,759,760,761,762,763,764,765,766,767,768,769,770,771,772,773,774,775,776,777,778,779,780,781,782,783,784,785,786,787,788,789,790,791,792,793,794,795,796,797,798,799,800,801,802,803,804,805,806,807,808,809,810,811,812,813,814,815,816,817,818,819,820,821,822,823,824,825,826,827,828,829,830,831,832,833,834,835,836,837,838,839,840,841,842,843,844,845,846,847,848,849,850,851,852,853,854,855,856,857,858,859,860,861,862,863,864,865,866,867,868,869,870,871,872,873,874,875,876,877,878,879,880,881,882,883,884,885,886,887,888,889,890,891,892,893,894,895,896,897,898,899,900,901,902,903,904,905,906,907,908,909,910,911,912,913,914,915,916,917,918,919,920,921,922,923,924,925,926,927,928,929,930,931,932,933,934,935,936,937,938,939,940,941,942,943,944,945,946,947,948,949,950,951,952,953,954,955,956,957,958,959,960,961,962,963,964,965,966,967,968,969,970,971,972,973,974,975,976,977,978,979,980,981,982,983,984,985,986,987,988,989,990,991,992,993,994,995,996,997,998,999,1000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 10:50

